



SST02

Fingerprint Identification Factsheet

Bright black



Operating Conditions of Module

- ✓ Operating temperature : -20°C~70°C
- ✓ Humidity : 5% ~ 95%
- ✓ Atmospheric pressure : 86 kPa ~ 106kPa

Electro-optical Characteristics

Item	Description	specification	Unit
Working Voltage	AVDD	3.3	V
Sleep mode current	Sleep	40	uA
I/O supply Voltage	VDDIO	1.8	V
Working current	Image Capture	8.5	mA

Basic Specifications of Module

Item	Typical Value
Sensor IC	Supplier: 茂丞 PN: JMT3118
Identification principle	Capacitive sensing
ID exposed size	6*22.91mm
Graphics output primitive	120*60 Pixel
dpi	423
Identification area	7.2*3.6mm
Data interface	SPI
Interrupt wake-up function	Yes
Interrupt wake-up power consumption	120uA
FAR/FRR	FRR<3% , FAR Target 1/50,000
Coating color	Bright black
Waterproof level	IPX8

2D Diagram of Structure and Critical Dimension Requirements

PIN	DEFINE
1	GND
2	HOMEKEY
3	RST_N
4	MISO
5	CS_N
6	IRQ
7	GND
8	SPCLK
9	AVDD
10	MOSI
11	VDDIO
12	FP_ID

Note:

- Chip NO.: JMT3118A.
- 本产品环保要求: 需符合RoHS要求;
- Coating: 高亮黑
- 金属环: 暗光银色, AL6063+表面哑光+阳极氧化+底部镀锡, 金属环需要接地处理
- 所有钢片补强均需接地处理, 钢片补强外形不得超出FPC, 钢片补强接地阻抗 $\leq 10\Omega$, 钢片补强材质: SUS304, 硬度要求: H
- 标注 \varnothing 为关键尺寸; 标注 \ominus 需要做CPK查看;
- 未注公差 $\pm 0.15\text{mm}$.

REV	Revision Description	DRAWN BY	CHK BY	ISSUE DATE
R05	1. 补强片内部整型及折弯	XAO		2018/02/22
R04	1. 调整钢片PC板孔位间距	XAO		2017/5/10
R03	1. 增加贴片 ESWPACAJA 型号及 VSWACDIA; 2. 增加连接器内部触点间距; 3. 增加PIN DEFIN	XAO		2017/5/9
R02	1. 补强片外形由 5mm 补强板改为 4mm 补强板; 2. 补强板厚度由 0.15mm 改为 0.15mm; 3. 补强板孔径由 0.8mm 改为 0.8mm	XAO		2017/5/5
R01	1. 元器件调整间距材料厚度增加; 2. 元器件间距增加; 3. 增加贴片间距; 4. 增加贴片间距; 5. 增加贴片间距	XAO		2017/4/26
R00	None Release			2017/4/20

Revision History

IF NO SPECIALLY SPECIFIED							
.X	+/-0.1	.XXX	+/-0.05	TITLE	成品圖		
.XX	+/-0.1	ANG	+/-0.5	REV.	R05	UNIT	mm
PAGE 1 of 1				UNIT	mm	Strip	85.78*27.04*2.90
DWN BY	XIAO	DATE	2018/02/22	SIZE	A4	Material	See Notes
CHK BY		DATE		SCALE	1:1	3rd ANGLE	